

TSMC-01-413

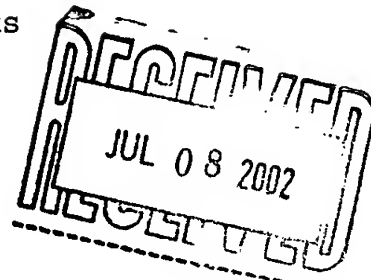


2812
#3
7-8-2

April 3, 2002

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603



Subject:

Serial No. 10/060,483 01/30/02

Yen-Ming Chen et al.

NOVEL METHOD TO IMPROVE BUMP
RELIABILITY FOR FLIP CHIP DEVICE

Grp. Art Unit: 2812

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on April 10, 2002.

Stephen B. Ackerman, Reg.# 3776

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SBA 4/10/02

U.S. Patent 5,543,253 to Park et al., "Photomask for T-Gate Formation and Process for Fabricating the Same," discusses a dual damascene like Photo process for a T-gate.

U.S. Patent 6,042,996 to Lin et al., "Method of Fabricating a Dual Damascene Structure," discusses a dual damascene process.

The following four U.S. Patents disclose Bump and UBM processes:

- 1) U.S. Patent 6,232,212 to Degani et al., "Flip Chip Bump Bonding."
- 2) U.S. Patent 6,153,503 to Lin et al., "Continuous Process for Producing Solder Bumps on Electrodes of Semiconductor Chips."
- 3) U.S. Patent 6,130,141 to Degani et al., "Flip Chip Metallization."
- 4) U.S. Patent 6,118,180 to Loo et al., "Semiconductor Die Metal Layout for Flip Chip Packaging."

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

TSMC-01-413

Application Number

10/060,483

Applicant

Yen-Ming Chen et al.

Filing Date

01/30/02

Group Art Unit

2812

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5543253	8/6/96	Park et al.	439	5	12/16/94
	6042996	3/28/00	Lin et al.	430	313	4/13/98
	6232212	5/15/01	Degani et al.	438	612	2/23/99
	6153503	11/28/00	Lin et al.	438	613	3/10/98
	6130141	10/10/00	Degani et al.	438	455	10/14/98
	6118180	9/12/00	Loe et al.	257	737	11/3/97

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.